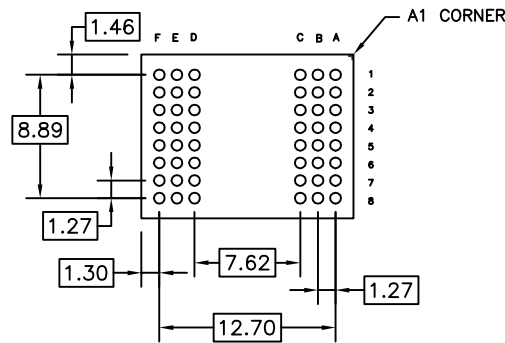
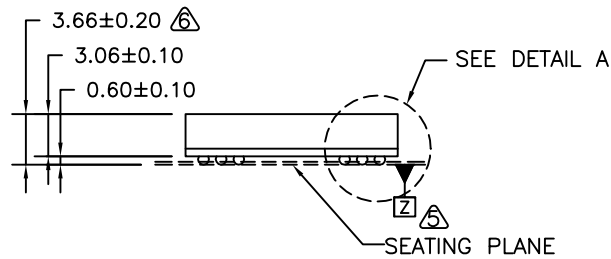


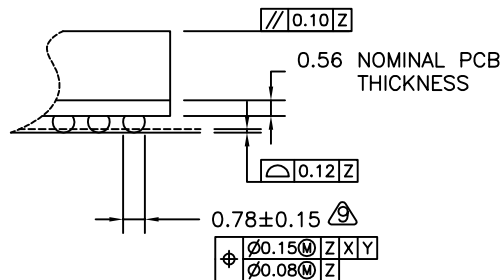
TOP VIEW



BOTTOM VIEW



SIDE VIEW



DETAIL A

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS UNLESS OTHERWISE SPECIFIED.
2. DIMENSION & TOLERANCE PER ASMEY14.5M-1994.
3. MATERIAL MUST COMPLY WITH BANNED AND RESTRICTED SUBSTANCES SPEC #10-0131.
4. THE BASIC SOLDER BALL GRID PITCH IS 1.27 MM.
5. PRIMARY DATUM Z AND SEATING PLANES ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. THIS DIMENSION INCLUDES STAND-OFF HEIGHT AND PACKAGE BODY THICKNESS.
7. A1 CORNER MUST BE IDENTIFIED BY LASER MARK ON TOP PACKAGE.
8. BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
9. DIMENSION MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM Z.
10. ALL DIMENSIONS APPLY TO LEADED (-), LEAD FREE (+), ROHS (#) EXEMPT PKG. CODES.
11. PACKAGE CODE: V48-H1, V48+H1, V48#H1



TITLE: PACKAGE OUTLINE, 48 BALLS PBGA, W/ CRYSTAL 11.80.x15.30x3.66mm, 1.27mm PITCH, 2 LAYER			
APPROVAL	DOCUMENT CONTROL NO. 21-0364	REV. C	1/1

-DRAWING NOT TO SCALE-